



## Material Content Data Sheet



<b>Sales Product Name</b>		IDV08E65D2		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000997630							
<b>Package</b>		PG-TO220-2-22		<b>Weight*</b>		2175.58 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.330	0.02	0.02	152	152	
leadframe	non noble metal	iron	7439-89-6	1.053	0.05		484		
	inorganic material	phosphorus	7723-14-0	0.316	0.01		145		
	non noble metal	copper	7440-50-8	1051.163	48.33	48.39	483165	483794	
wire	non noble metal	aluminium	7429-90-5	1.283	0.06	0.06	590	590	
encapsulation	organic material	carbon black	1333-86-4	2.229	0.10		1025		
	plastics	epoxy resin	-	209.516	9.63		96303		
	inorganic material	silicondioxide	60676-86-0	902.702	41.49	51.22	414924	512252	
leadfinish	non noble metal	tin	7440-31-5	5.465	0.25	0.25	2512	2512	
plating	non noble metal	nickel	7440-02-0	1.114	0.05		512		
	inorganic material	phosphorus	7723-14-0	0.003	0.00	0.05	1	513	
solder	non noble metal	antimony	7440-36-0	0.041	0.00		19		
	noble metal	silver	7440-22-4	0.101	0.00		47		
	non noble metal	tin	7440-31-5	0.263	0.01	0.01	121	187	
*deviation	< 10%					Sum in total:	100,00		1000000

### Important Remarks:

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